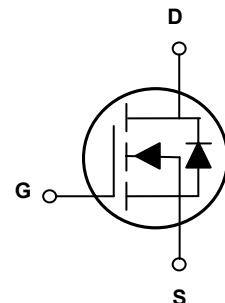
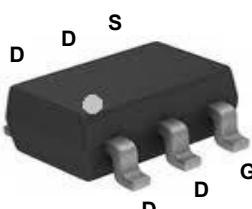


Main Product Characteristics

$V_{(BR)DSS}$	60V
$R_{DS(ON)}$	75mΩ
I_D	2.9A



SOT-23-6L

Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF6912 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous ($T_A=25^\circ\text{C}$)	I_D	2.9	A
Drain Current – Continuous ($T_A=70^\circ\text{C}$)		2.3	A
Drain Current – Pulsed ¹	I_{DM}	11.6	A
Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	1	W
Power Dissipation – Derate above 25°C		0.008	W/ $^\circ\text{C}$
Storage Temperature Range	T_{STG}	-50 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-50 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	125	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	---	---	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	---	0.05	---	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DS}}^{\text{SS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2\text{A}$	---	60	75	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=1.5\text{A}$	---	70	90	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		---	-5	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=1\text{A}$	---	7	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{2, 3}	Q_g	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=2\text{A}$	---	9.3	14	nC
Gate-Source Charge ^{2, 3}	Q_{gs}		---	2.1	4	
Gate-Drain Charge ^{2, 3}	Q_{gd}		---	1.8	4	
Turn-On Delay Time ^{2, 3}	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=30\text{V}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=3.3\Omega, I_{\text{D}}=1\text{A}$	---	2.9	6	nS
Rise Time ^{2, 3}	T_r		---	9.5	18	
Turn-Off Delay Time ^{2, 3}	$T_{\text{d}(\text{off})}$		---	18.4	35	
Fall Time ^{2, 3}	T_f		---	5.3	10	
Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	---	500	725	pF
Output Capacitance	C_{oss}		---	45	65	
Reverse Transfer Capacitance	C_{rss}		---	16	30	
Gate Resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	---	2	4	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_{\text{G}}=V_{\text{D}}=0\text{V}$, Force Current	---	---	2.9	A
Pulsed Source Current	I_{SM}		---	---	5.8	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=1\text{A}, T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time ²	t_{rr}	$V_{\text{GS}}=30\text{V}, I_{\text{s}}=1\text{A}, dI/dt=100\text{A}/\mu\text{s}, T_J=25^\circ\text{C}$	---	23.2	---	nS
Reverse Recovery Charge ²	Q_{rr}		---	14.3	---	nC

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

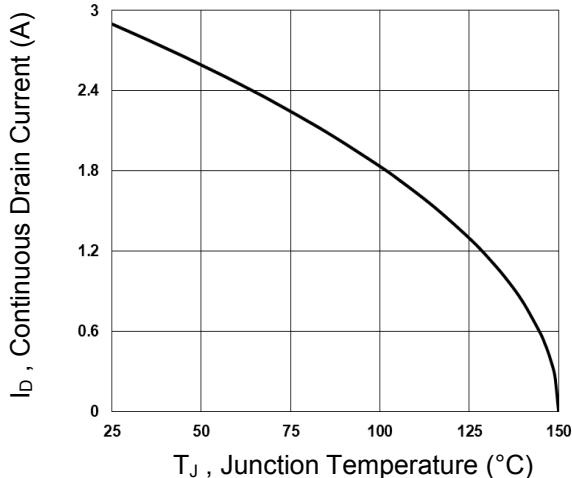


Fig.1 Continuous Drain Current vs. T_J

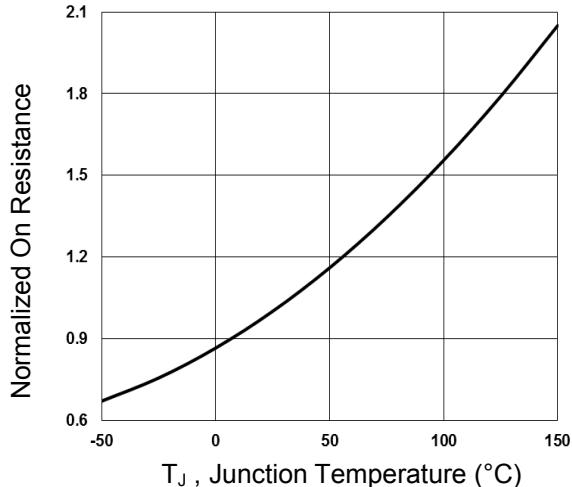


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

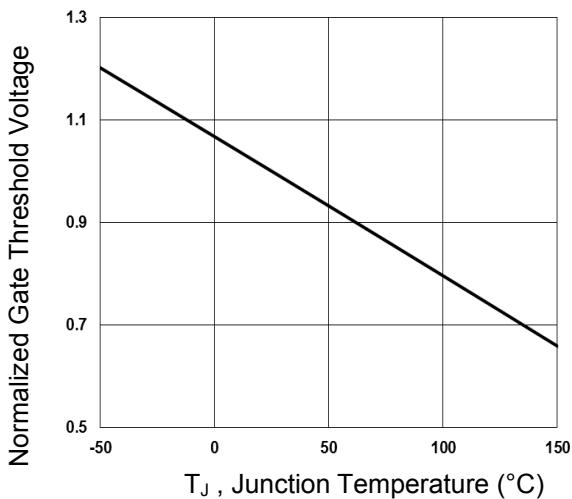


Fig.3 Normalized V_{th} vs. T_J

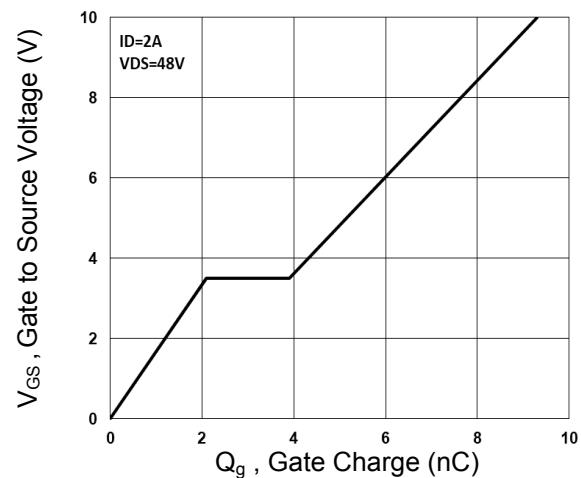


Fig.4 Gate Charge Waveform

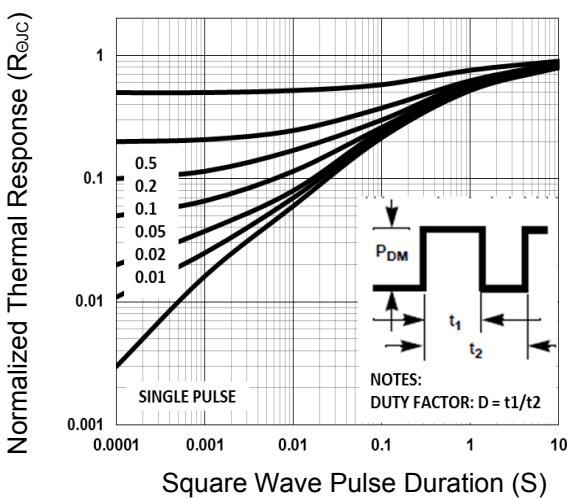


Fig.5 Normalized Transient Response

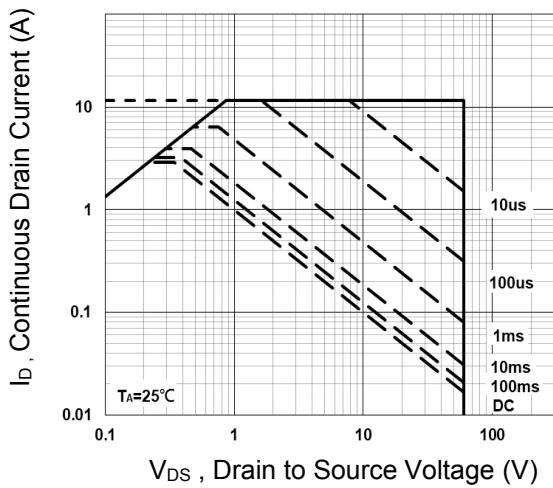


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

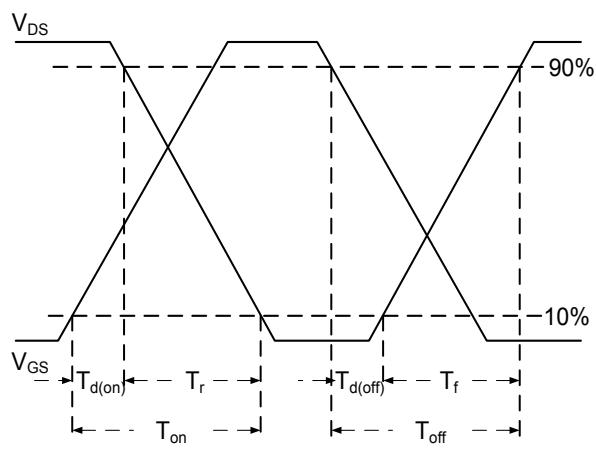


Fig.7 Switching Time Waveform

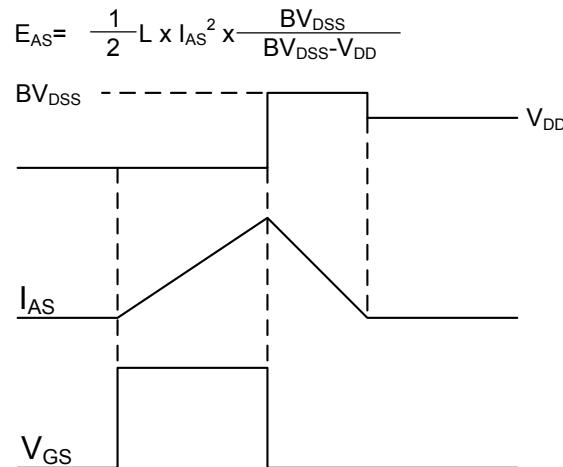
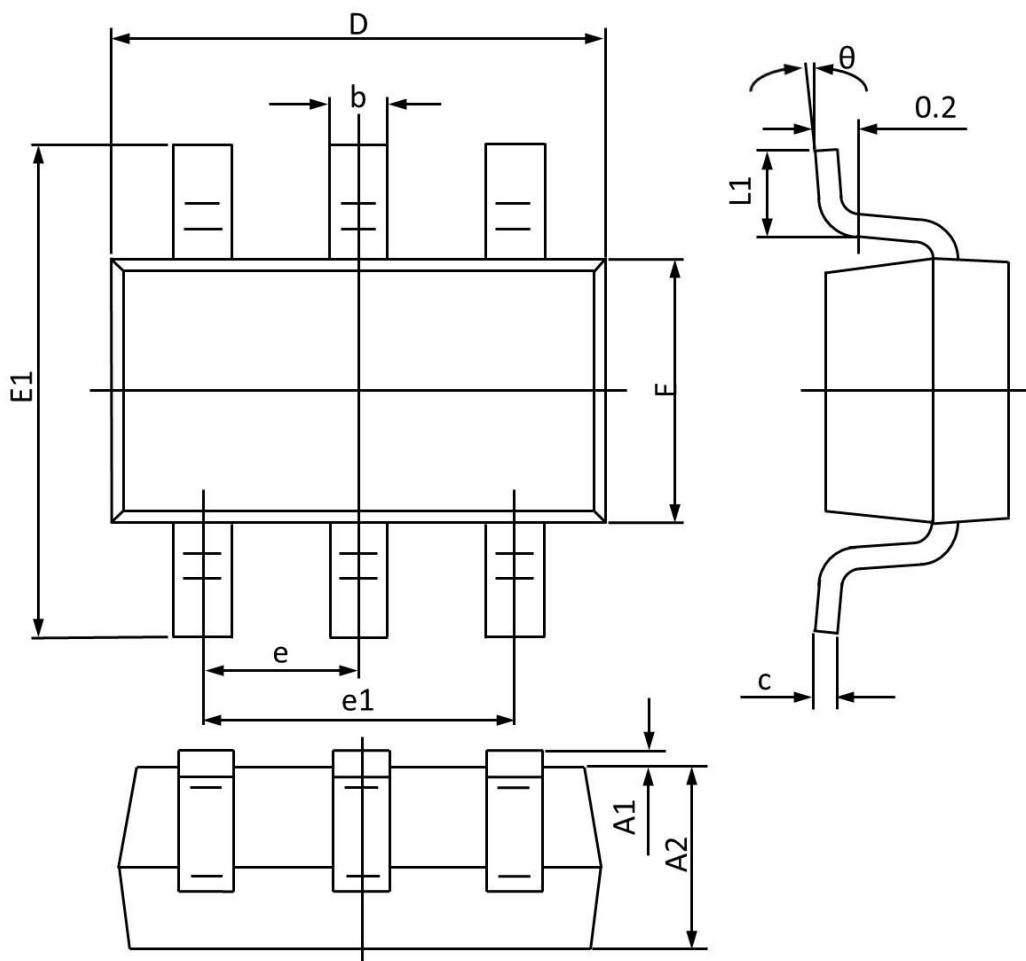


Fig.8 E_{AS} Waveform

Package Outline Dimensions

SOT-23-6L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.040	0.047
b	0.300	0.500	0.012	0.019
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E1	2.600	3.000	0.103	0.118
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.550	0.010	0.021
θ	0°	8°	0°	8°